Dual Bias Resistor Transistors

NPN and PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base–emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the EMD5DXV6 series, two complementary BRT devices are housed in the SOT–563 package which is ideal for low power surface mount applications where board space is at a premium.

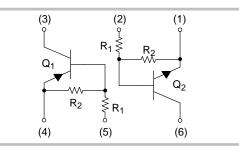
Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7 inch Tape and Reel
- Lead Free Solder Plating
- These Devices are Pb-Free and are RoHS Compliant



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SOT-563 CASE 463A

MARKING DIAGRAM



U5 = Specific Device Code

M = Month Code

= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
EMD5DXV6T5G	SOT–563 (Pb–Free)	8000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted, common for Q_1 and Q_2 , – minus sign for Q_1 (PNP) omitted)

Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current	Ι _C	100	mAdc

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)		Symbol	Max	Unit
Total Device Dissipation Derate above 25°C	T _A = 25°C	PD	357 (Note 1) 2.9 (Note 1)	mW mW/°C
Thermal Resistance	Junction-to-Ambient	R _{θJA}	350 (Note 1)	°C/W
	Characteristic (Both Junctions Heated) Symbol		Max	Unit
Total Device Dissipation Derate above 25°C	T _A = 25°C	PD	500 (Note 1) 4.0 (Note 1)	mW mW/°C
Thermal Resistance	Junction-to-Ambient	R _{0JA}	250 (Note 1)	°C/W
Junction and Storage Temperature		T _J , T _{stg}	–55 to +150	°C

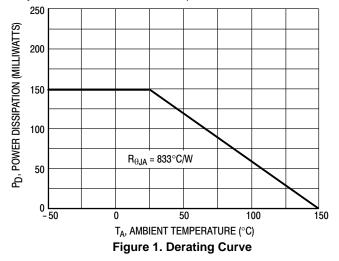
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad

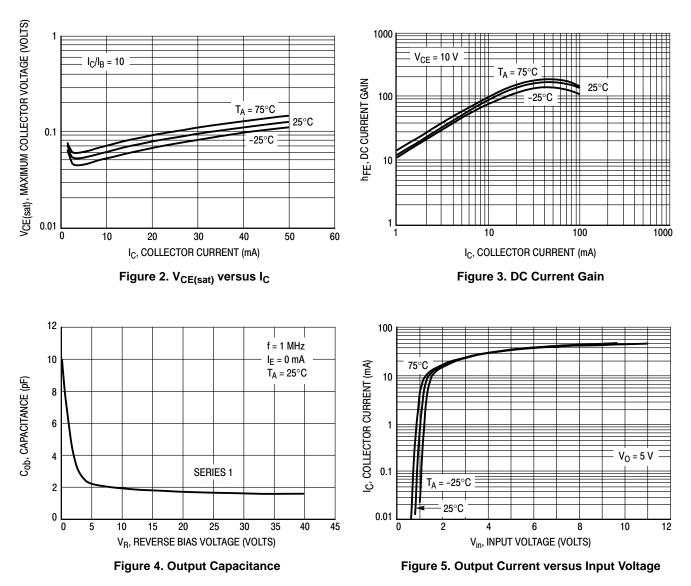
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

ELECTRICAL CHARACTERISTICS (T _A = 25°C unless otherw			<u> </u>	I	1
Characteristic	Symbol	Min	Тур	Max	Unit
Q1 TRANSISTOR: PNP					
OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V_{CB} = 50 V, I _E = 0)	I _{CBO}	I	-	100	nAdc
Collector-Emitter Cutoff Current ($V_{CB} = 50 \text{ V}, I_B = 0$)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current (V_{EB} = 6.0, I_{C} = 5.0 mA)	I _{EBO}	-	-	1.0	mAdc
ON CHARACTERISTICS					
Collector-Base Breakdown Voltage ($I_C = 10 \ \mu A$, $I_E = 0$)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 2.0 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
DC Current Gain (V_{CE} = 10 V, I _C = 5.0 mA)	h _{FE}	20	35	-	1
Collector–Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$)	V _{CE(SAT)}	-	-	0.25	Vdc
Output Voltage (on) (V _{CC} = 5.0 V, V _B = 2.5 V, R _L = 1.0 k Ω)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, R_L = 1.0 k\Omega)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	3.3	4.7	6.1	kΩ
Resistor Ratio	R1/R2	0.38	0.47	0.56	
Q2 TRANSISTOR: NPN					
OFF CHARACTERISTICS					
Collector-Base Cutoff Current ($V_{CB} = 50 \text{ V}, I_E = 0$)	I _{CBO}	_	-	100	nAdc
Collector-Emitter Cutoff Current ($V_{CB} = 50 \text{ V}, I_B = 0$)	I _{CEO}	_	-	500	nAdc
Emitter-Base Cutoff Current ($V_{EB} = 6.0$, $I_C = 5.0$ mA)	I _{EBO}	_	-	0.1	mAdc
ON CHARACTERISTICS	-				
Collector-Base Breakdown Voltage ($I_C = 10 \ \mu A$, $I_E = 0$)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_{C} = 2.0 \text{ mA}, I_{B} = 0$)	V _{(BR)CEO}	50	-	-	Vdc
DC Current Gain (V _{CE} = 10 V, I_C = 5.0 mA)	h _{FE}	80	140	_	
Collector–Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$)	V _{CE(SAT)}	_	-	0.25	Vdc
Output Voltage (on) (V _{CC} = 5.0 V, V _B = 2.5 V, R _L = 1.0 k Ω)	V _{OL}	_	-	0.2	Vdc
Output Voltage (off) (V _{CC} = 5.0 V, V _B = 0.5 V, R _L = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	33	47	61	kΩ

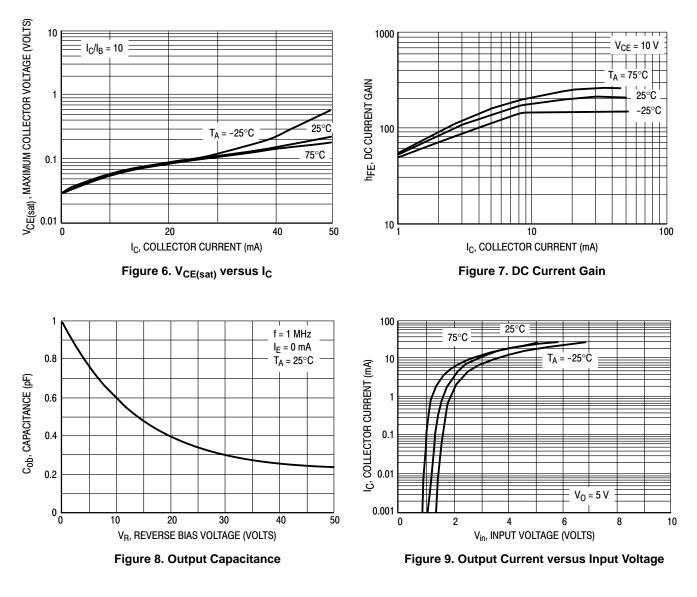
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



TYPICAL ELECTRICAL CHARACTERISTICS — EMD5DXV6 PNP TRANSISTOR



TYPICAL ELECTRICAL CHARACTERISTICS — EMD5DXV6 NPN TRANSISTOR



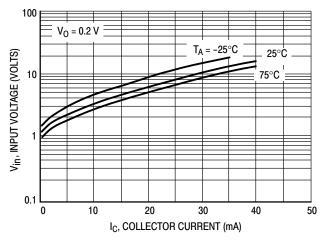


Figure 10. Input Voltage versus Output Current

6Х





SOT-563, 6 LEAD CASE 463A ISSUE H

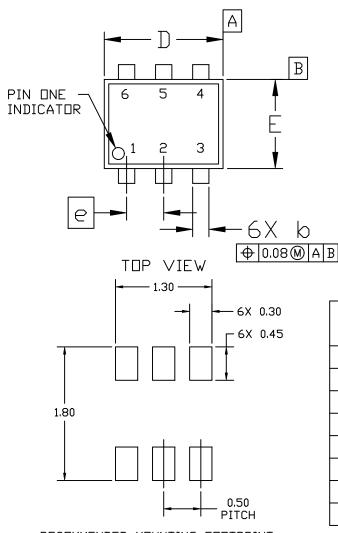
DATE 26 JAN 2021

ALE 4:1

NDTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.

А

- 1. DIMENSIONING AND TOLERANCING PER A 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS DF BASE MATERIAL.



SIDE VIEW MILLIMETERS DIM MIN. NDM. MAX. 0.50 0.55 0.60 Α 0.17 0.22 0.27 b 0.08 0.13 0.18 С 1.50 1.60 1.70 D Ε 1.10 1.20 1.30 0.50 BSC e L 0.10 0.20 0.30 H_E 1.50 1.60 1.70

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RECOMMENDED MOUNTING FOOTPRINT* * For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHIDE 1
2. BASE 1	2. EMITTER 2	2. CATHIDE 1
3. COLLECTOR 2	3. BASE 2	3. ANUDE/ANUDE 2
4. EMITTER 2	4. COLLECTOR 2	4. CATHIDE 2
5. BASE 2	5. BASE 1	5. CATHIDE 2
6. COLLECTOR 1	6. COLLECTOR 1	6. ANUDE/ANUDE 1
STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. COLLECTOR	PIN 1. CATHEDE	PIN 1. CATHODE
2. COLLECTOR	2. CATHEDE	2. ANODE
3. BASE	3. ANEDE	3. CATHODE
4. EMITTER	4. ANEDE	4. CATHODE
5. COLLECTOR	5. CATHEDE	5. CATHODE
6. COLLECTOR	6. CATHEDE	6. CATHODE
STYLE 7:	STYLE 8:	STYLE 9:
PIN 1. CATHODE	PIN 1. DRAIN	PIN 1. SDURCE 1
2. ANODE	2. DRAIN	2. GATE 1
3. CATHODE	3. GATE	3. DRAIN 2
4. CATHODE	4. SDURCE	4. SDURCE 2
5. ANODE	5. DRAIN	5. GATE 2
6. CATHODE	6. DRAIN	6. DRAIN 1
STYLE 10: PIN 1. CATHIDE 1 2. N/C 3. CATHIDE 2 4. ANIDE 2 5. N/C 6. ANIDE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

6. COLLECTOR 2

DATE 26 JAN 2021

GENERIC **MARKING DIAGRAM***



XX = Specific Device Code

M = Month Code

. = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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